

## Features

- Compact solid-state bidirectional SiC MOSFETs
- Breakdown voltage  $V_{OFF}$  up to 1500V@ $I_{DSS}=100\mu A$
- Low output leakage current,  $I_O=1\mu A@V_{DS}=1000V$
- Low on-resistance,  $R_{ON}(Typ)=100\ \Omega$  @ $I_O=2mA$
- Low turn on time:  $T_{ON}<50\mu s$
- Low turn off time:  $T_{OFF}<200\mu s$
- 7-V reverse breakdown voltage handling capability
- Stretched WB SOIC-12 package with >8 mm creepage and clearance
- CTI:>500V
- Temperature range:  $-40^{\circ}C$  to  $+125^{\circ}C$
- Safety Approval:
  - DIN VDE 0884-17:2021-10
  - UL 1577 component recognition program
  - CQC Gb4943.1-2022
- AEC-Q100 Qualified

Pai8558EQ is an opto compatible solid state relay developed based on Rongpai's unique isolation technology and mature standard semiconductor CMOS process. The device contains two SiC MOSFETs with bidirectional current up to 30mA and peak current up to 50mA.

The input is isolated from the output by a 5kVRMS isolation barrier. It integrates a gate driver which controls the opening and closing of the two MOSFETs on the output. The output switch is turned on when the input current exceeds 7mA, and turned off when the input voltage is lower than 0.4V.

The device uses a standard wide-body WB SOIC-12 package that provides 5kVrms and 10kVpeak insulation and extremely high reliability.

## Applications

- Battery/motor/solar panel insulation resistance measurement/leakage detection
- Sensing in high voltage application
- Electro mechanical relay replacement
- Inrush current limiter protection

## General Description

## Pin Configurations and Functions

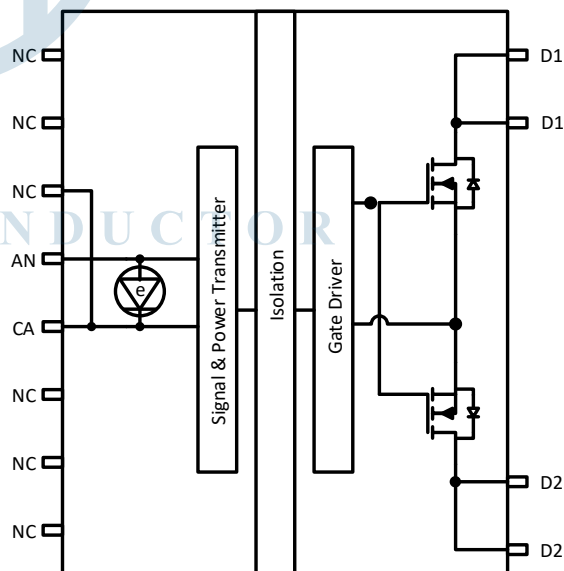
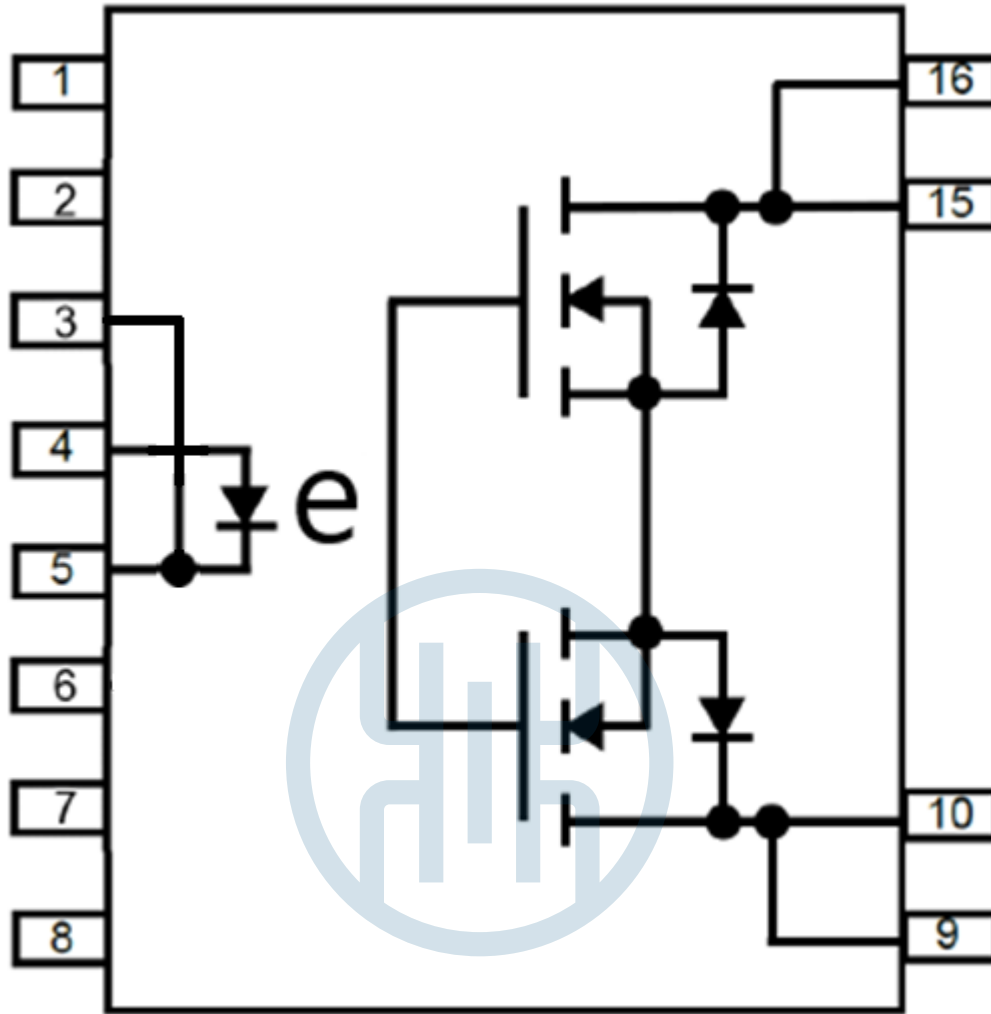


Fig.1 Functional Block Diagram



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Table 1.Pai8558EQ Pin Function Descriptions

PIN NO.	PIN NAME	TYPE	DESCRIPTION
1,2,6,7,8	NC	-	No connection.
3	NC	-	Do not connect (internally connected to Pin 5).
4	AN	I	Anode.
5	CA	I	Cathode.
9,10	D2	O	Drain1.
15,16	D1	O	Drain2.

## Specifications

## Absolute Maximum Ratings

Table 2.Absolute Maximum Ratings ( $T_A = 25^{\circ}\text{C}$ , unless otherwise noted.)

Parameter	Symbol	Condition	Min	Max	Unit
Average input current	$I_{F(\text{avg})}$	$T_A = -40^{\circ}\text{C}$ to $125^{\circ}\text{C}$		30	mA
Surge input current	$I_{F(\text{surge})}$	$f=1\text{Hz}$ , 50% duty		60	mA
Peak transient input current	$I_{FP}$	$f=100\text{Hz}$ , duty cycle=0.1%		1	A
Reverse input voltage	$BV_R$	$T_A = -40^{\circ}\text{C}$ to $125^{\circ}\text{C}$		7	V
Input power dissipation	$P_{IN}$			65	mW
Output load current	$I_O$	$T_A = -40^{\circ}\text{C}$ to $125^{\circ}\text{C}$		50	mA
Output avalanche current	$I_{AV}$	$t_m = 1 \text{ min}$ , duty cycle = 0.1%, cumulative of 5 mins over lifetime		0.6	mA
Output power dissipation	$P_O$			1000	mW
Junction temperature, $T_J$	$T_J$		-40	150	$^{\circ}\text{C}$
Ambient temperature, $T_A$	$T_A$		-40	125	$^{\circ}\text{C}$
Storage temperature, $T_{stg}$	$T_{stg}$		-55	150	$^{\circ}\text{C}$

- 1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## ESD Ratings

Table 3.ESD Ratings

Model	Symbol	Condition	Min	Max	Unit
Human-body model	HBM	Per AEC Q100-001	2000		V
Charge-device model	CDM	Per AEC Q100-005	750		V

## Recommended Operating Conditions

Table 4.Recommended Operating Conditions (Over operating free-air temperature range (unless otherwise noted)

Symbol	Description	MIN	MAX	UNIT
$I_{F(\text{ON})}$	Input current(ON)	7	20	mA
$V_{F(\text{OFF})}$	Input voltage (OFF)	-5	0.4	V
$V_O$	Continuous load voltage		1000	V
$I_O$	Load current	-10	10	mA
$T_A$	Ambient Temperature	-40	125	$^{\circ}\text{C}$

## Insulation Specifications

Table 5.Insulation Specifications

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
$V_{IORM}$	Maximum working insulation voltage			1414		$V_{PEAK}$
$V_{IOTM}$	Transient overvoltage	Transient Overvoltage, $t_{ini} = 60 \text{ sec}$	7071			$V_{PEAK}$
$V_{ISO}$	Input-Output Momentary Withstand Voltage	$RH \leq 50\%$ , $t_m = 1 \text{ minute}$ ; $T_A = 25^{\circ}\text{C}$	5000			$V_{RMS}$
$V_{IOSM}$	Surge voltage	Tested per VDE0884-11 with surge voltage of $1.2 \mu\text{s}/50 \mu\text{s}$ tested with magnitude $6250 \text{ V} \times 1.6 = 10 \text{ kV}$	6250			$V_{PEAK}$
$R_S$	Insulation Resistance at $T_S$	$V_{IO} = 500 \text{ V}$	$10^9$			$\Omega$
$R_{I-O}$	Input-Output Resistance	$V_{I-O} = 1000 \text{ VDC}$	$10^9$	$10^{14}$		$\Omega$
$C_{I-O}$	Input-Output Capacitance	$f = 1 \text{ MHz}$ ; $V_{I-O} = 0 \text{ VDC}$		0.6		pF

## Specifications

### Electrical Characteristics

Table 6. ELECTRICAL CHARACTERISTICS

Typical value is tested under  $T_A = 25^\circ\text{C}$ ,  $I_F = 10\text{mA}$ , unless otherwise specified.

Symbol	Parameter	Test condition	Min	Typ	Max	Unit	Fig.
$V_R$	Input reverse breakdown voltage	$I_R = 10\mu\text{A}$	5			V	
$V_{F(ON)}$	Input forward voltage	$I_F = 10\text{mA}$	1.9	2.0	2.2	V	
$V_{F(OFF)}$	Input-forward voltage(OFF)				0.4	V	
$I_{F(ON)}$	Input current(ON)		1		7	mA	
$ V_{O(OFF)} $	Output withstand voltage	$I_O = 100\mu\text{A}$ , $T_A = 25^\circ\text{C}$	1500			V	
$I_{O(OFF)}$	Output leakage current	$V_O = 1000\text{V}$ , $T_A = 25^\circ\text{C}$			1000	nA	
		$V_O = 1000\text{V}$ , $T_A = 125^\circ\text{C}$			1000	nA	
$C_{OUT}$	Output capacitance	$V_O = 0\text{V}$ , $f = 1\text{MHz}$		2.5		pF	
$R_{ON}$	Output Resistance	$I_O = 2\text{mA}$		120	250	$\Omega$	

### Switching Characteristics

Table 7. Switching Characteristics

Typical value is tested under  $T_A = 25^\circ\text{C}$ ,  $I_F = 10\text{mA}$ , unless otherwise specified.

Symbol	Parameter	Test condition	Min	Typ	Max	Unit	Fig.
$T_{ON}$	Turn-on time	$I_F = 10\text{mA}$ , $V_{DD} = 40\text{V}$ , $R_{LOAD} = 20\text{k}\Omega$	5	15	50	us	
$T_{OFF}$	Turn-off time	$V_{DD} = 40\text{V}$ , $R_{LOAD} = 20\text{k}\Omega$	10	64	200	us	

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### Typical Characteristics Curves

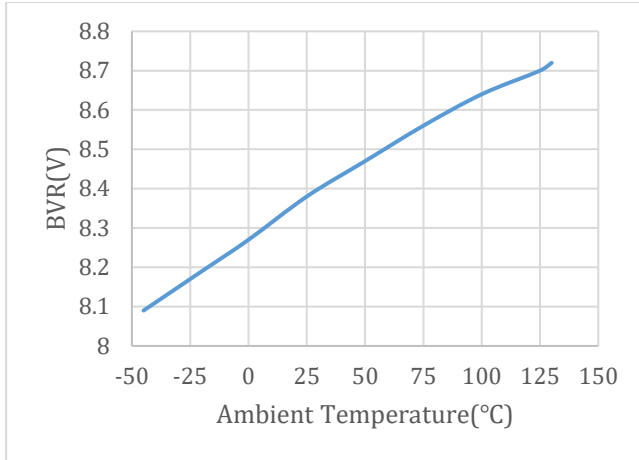


Fig3. BVR vs Ambient Temperature

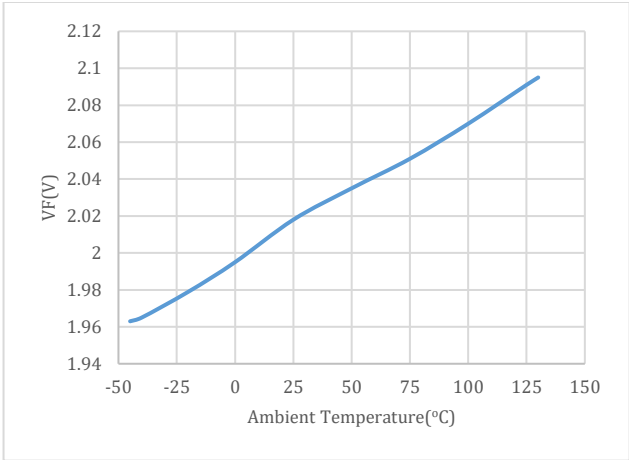


Fig4. Forward voltage vs Ambient Temperature

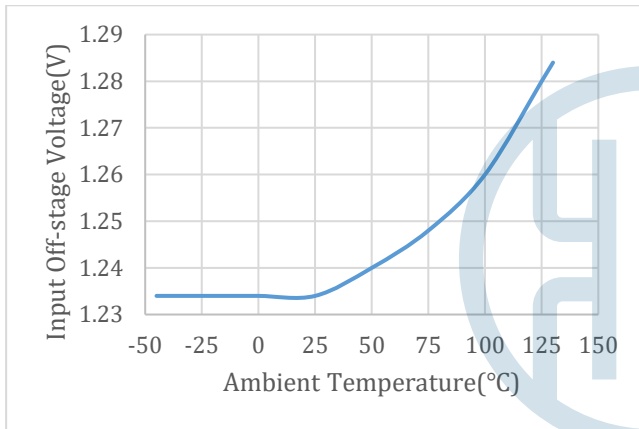


Figure 5 VF(OFF) vs Ambient Temperature

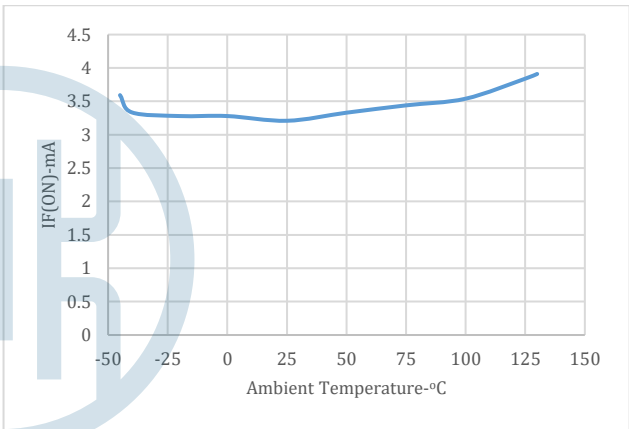


Figure 6 IF(ON) vs Temperature

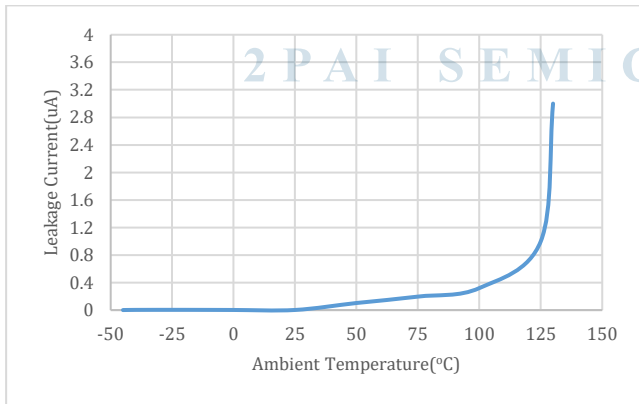


Figure 7 Leakage Current vs Ambient Temperature

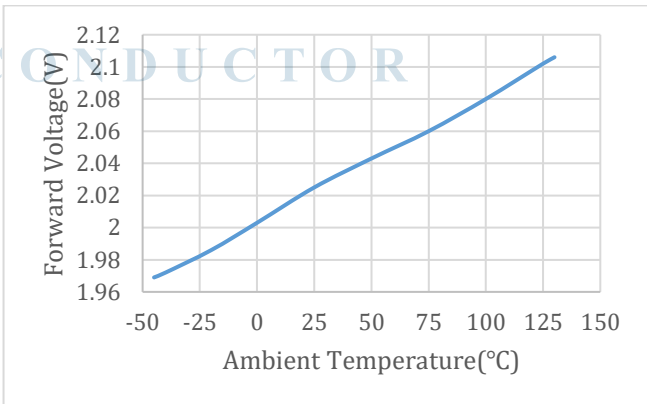


Figure 8 Forward voltage (VF) vs Temperature

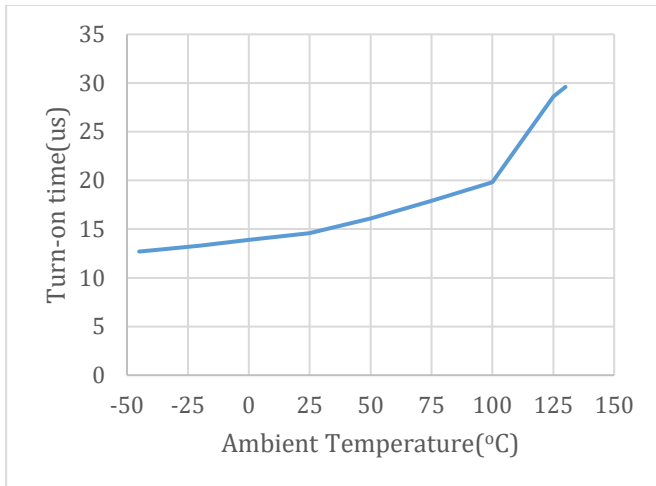
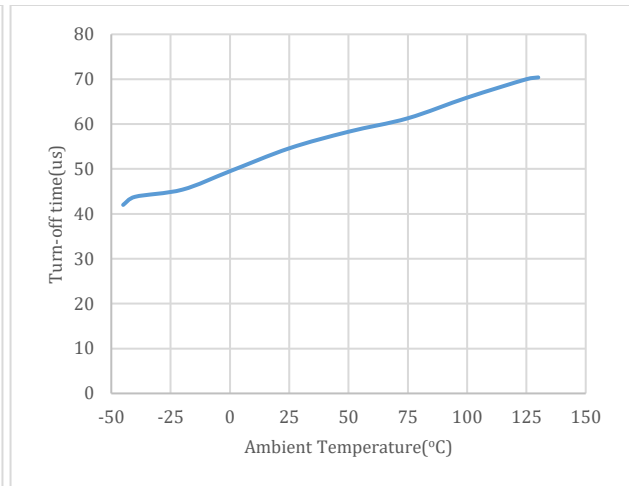
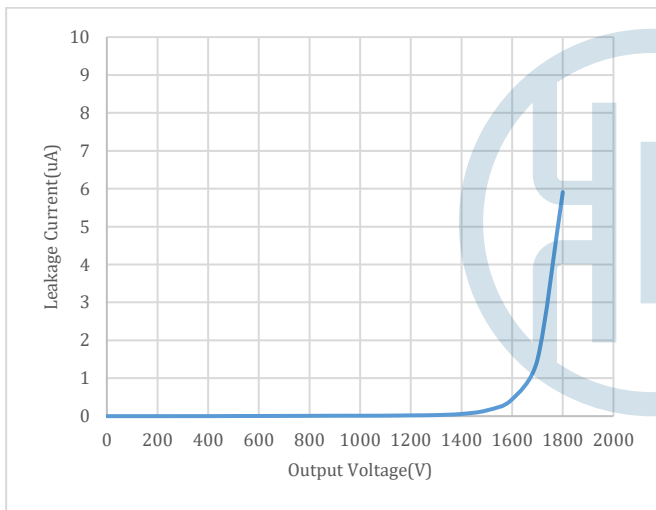
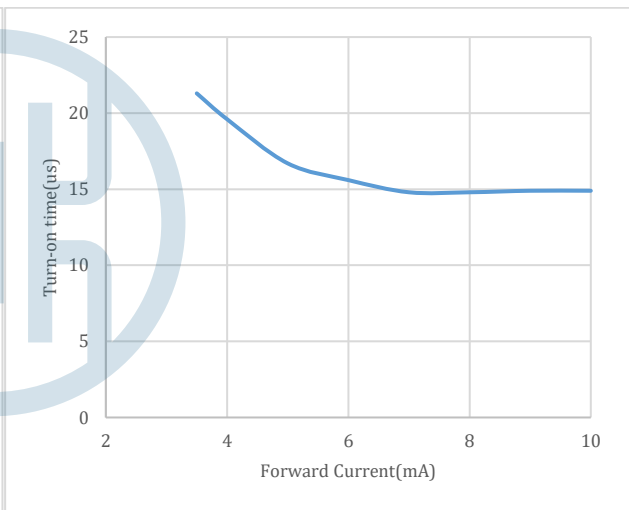
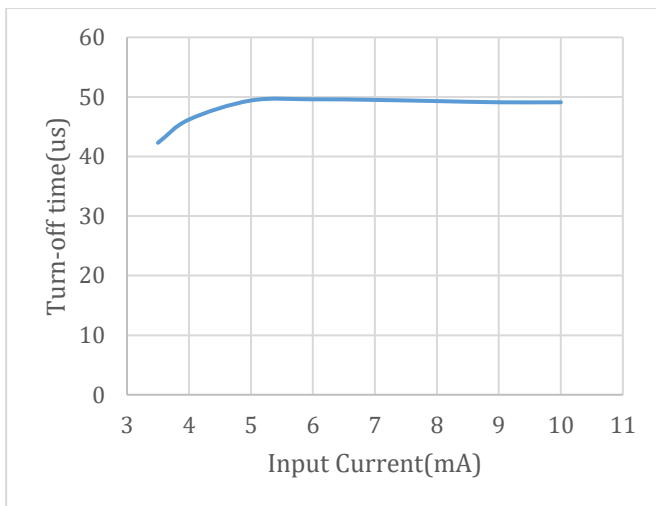

**Fig9. Turn-on time vs Ambient Temperature**

**Fig10. Turn-off time vs Ambient Temperature**

**Figure 11 Leakage Current vs Output Voltage**

**Figure 12 Turn-on time vs Forward Current**

**Figure 13 Turn-off time vs Forward Current**

Fig15.Switching Time Test Circuit and Waveform

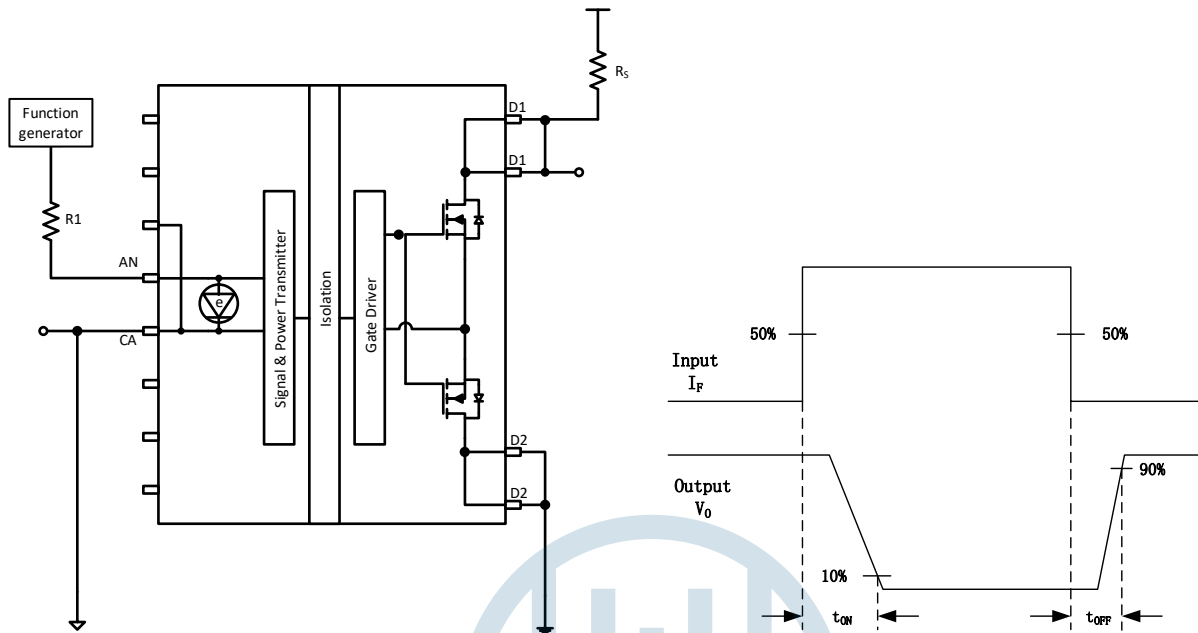
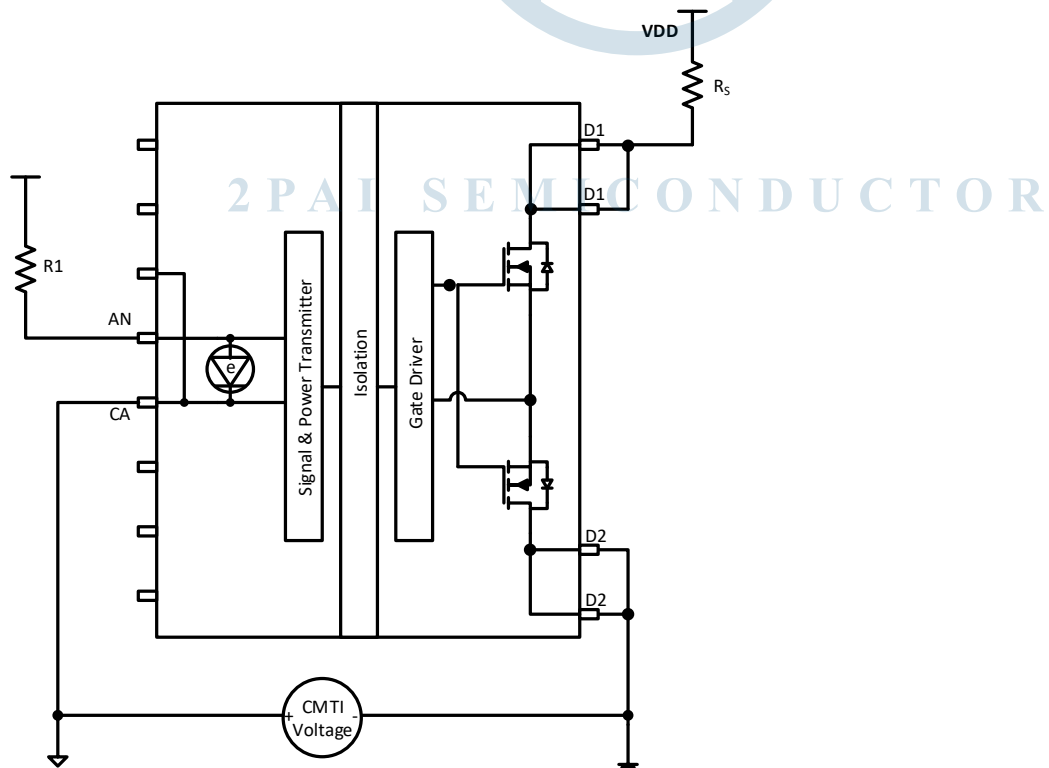


Fig16.CMTI Test Circuit



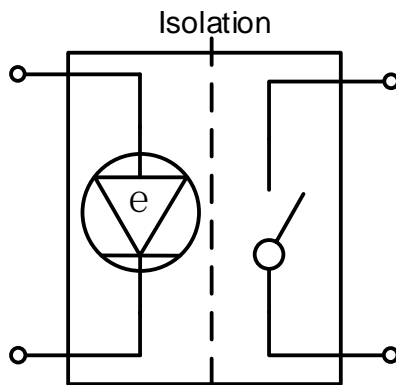
## Application Information

PAI8558EQ is a single channel isolated solid relay that is functionally equivalent to an optocoupler relay as shown in fig17. It functions like a bidirectional switch with no output power requirement. The input side is driven through an input voltage higher than 2.1V which can totally make the output side in on-state. The recommended input current is 7mA to 20mA.

the PAI8558EQ's input being controlled by the microprocessor to switch the output (high voltage side).

The Pai8558EQ 's galvanic isolation protects the low voltage side of the circuit (input) from the high-voltage side (output). Pins 9 and 10 are internally connected, and 15 and 16 are internally connected too. It is recommended to shorting pin9 to pin10, as well as pin15 to pin16 while routing the PCB layout.

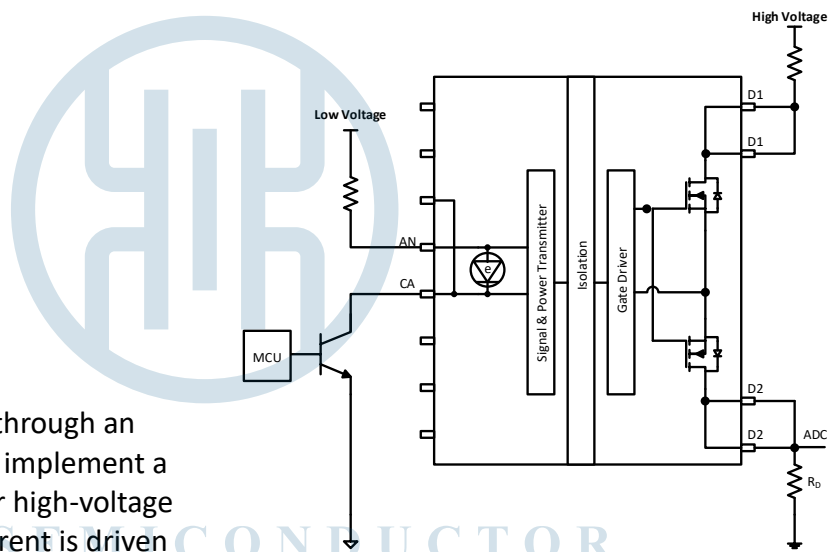
**Figure 17 Pai8558EQ Equivalent Circuit**



The input side energy is delivered through an on-chip power transfer block, and implement a driver circuitry to switch two inner high-voltage SiC MOSFETS. When sufficient current is driven into current input side controller, the internal power delivery circuit will be enabled. Then the energy in the input side will be delivered to the output side to supply output side drive circuitry to switch the inner two high-voltage SiC MOSFETS.

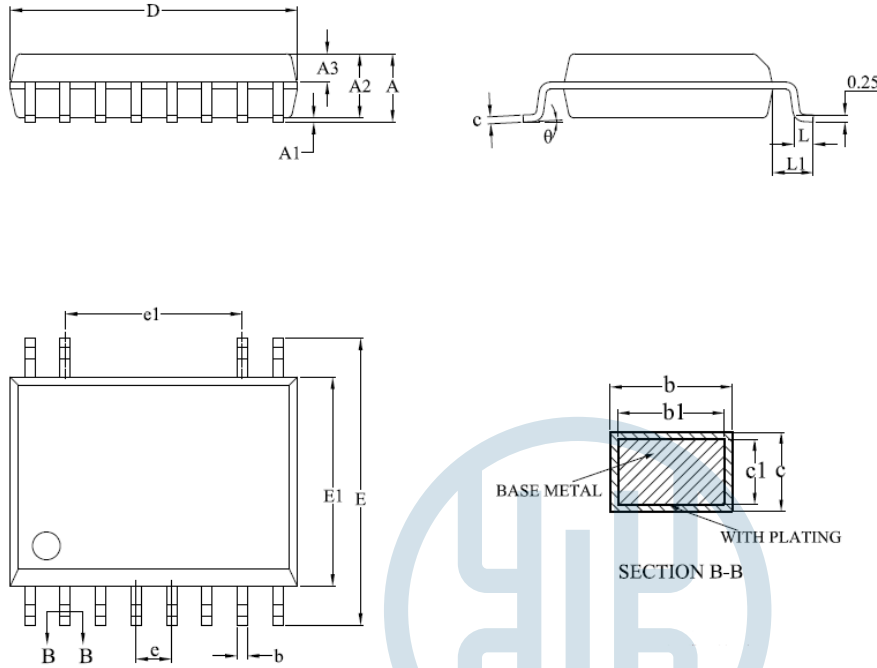
A typical application circuit (Figure 18) shows

**Figure 18 Typical Application Circuit**





## Package Dimension



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	2.65
A1	0.10	—	0.30
A2	2.25	2.30	2.35
A3	0.97	1.02	1.07
b	0.35	—	0.43
b1	0.34	0.37	0.40
c	0.25	—	0.29
c1	0.24	0.25	0.26
D	10.20	10.30	10.40
E	10.10	10.30	10.50
E1	7.40	7.50	7.60
e	1.27BSC		
e1	6.35BSC		
L	0.55	—	0.85
L1	1.40REF		
θ	0	—	8°

Fig 20. Outline Package for Pai855xE(Q)

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## Land pattern

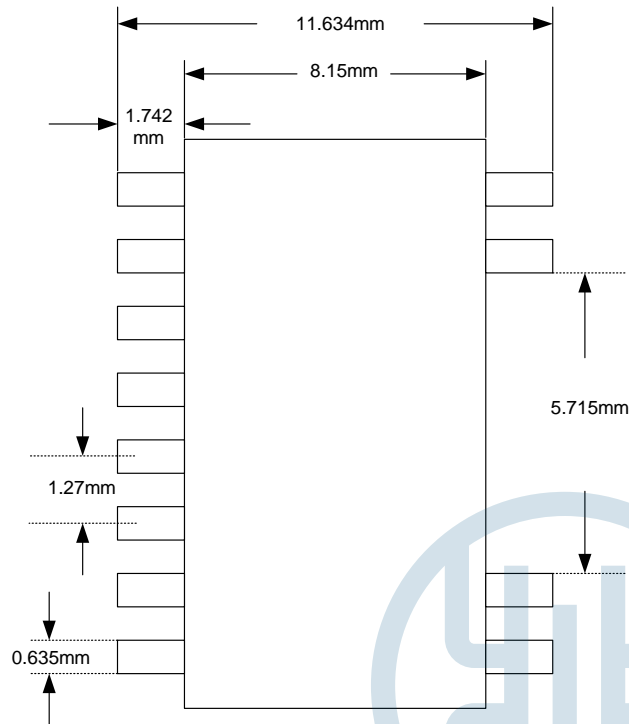


Fig 21. Outline Package

## 1. Top Marking



Fig 22. Top Marking

Line 1	XXXXXXXX=Product name
Line 2	YY = Work Year WW = Work Week ZZ=Manufacturing code from assembly house
Line 3	XXXX, no special meaning

## 2. Reel Information

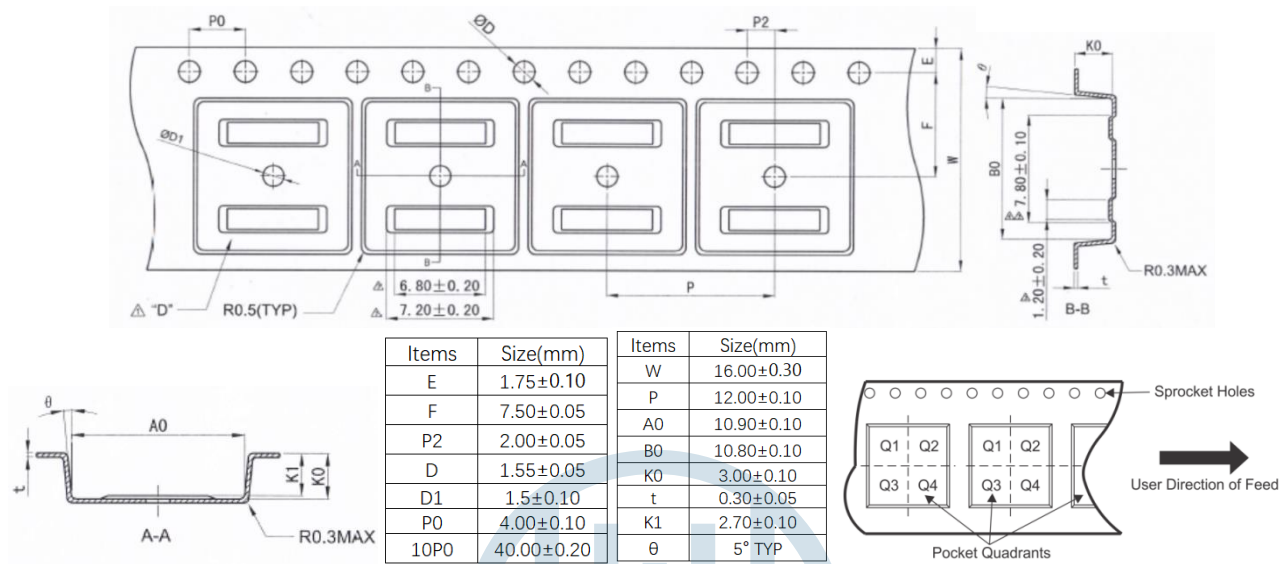


Fig 23. Reel Information

Note: The Pin 1 of the chip is in the quadrant Q1

## 3. Ordering Guide

Table 18. Ordering Guide

Model Name <sup>1</sup>	Temperature Range	Withstand Voltage Rating (kV rms)	Package	MSL Peak Temp <sup>2</sup>	Quantity per reel
Pai8558EQ - W2R	-40~125°C	5.0	WB SOIC-12	Level-2-260C-1Year	1500

<sup>1</sup>Paixxxxxx is equals to πxxxxxx in the customer BOM

<sup>2</sup>MSL, Peak Temp.- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

## 4. Important Notice And Disclaimer

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## 5. Revision History

Ver	Date	Page	Change Record
0.1	2021-03-18	All	Initial version
0.2	2022-11-04	Page1, page5, page6, page7, page8, page10	Delete Truth Table in page1, add curves in page5, page6, add package dimension in page10, change figures in page1, 7, and8, initial release



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